



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Michael E. Connell and Tongbi Jiang

Serial No.: 10/082,372

Filed: February 25, 2002

For: WAFER BACK SIDE COATING TO
BALANCE STRESS FROM PASSIVATION
LAYER ON FRONT OF WAFER AND BE
USED AS A DIE ATTACH ADHESIVE

Examiner: Unknown

Group Art Unit: 2812

Attorney Docket No.: 5083US (01-0428)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

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1.8(a)(1)(ii)

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PRELIMINARY AMENDMENT

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.